

Notice of References Cited	Application/Control No. 10/608,605	Applicant(s)/Patent Under Reexamination LEE ET AL.	
	Examiner Thomas J. Magee	Art Unit 2811	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,986,885	11-1999	Wyland, Christopher Paul	361/704
	B	US-6,084,295	07-2000	Horiuchi et al.	257/690
	C	US-6,620,720 B1	09-2003	Moyer et al.	438/612
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
	U	Syd R. Wilson, Clarence J. Tracy, and John L. Freeman, Jr., "Handbook of Multilevel Metallization for Integrated Circuits," Noyes Publ., Westwood, New Jersey (1993), pp. 868 - 872.			
	V	Electronic Packaging and Production, "Innovative PCB Reinforcement," (February, 1997), p.1			
	W				
	X				

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.